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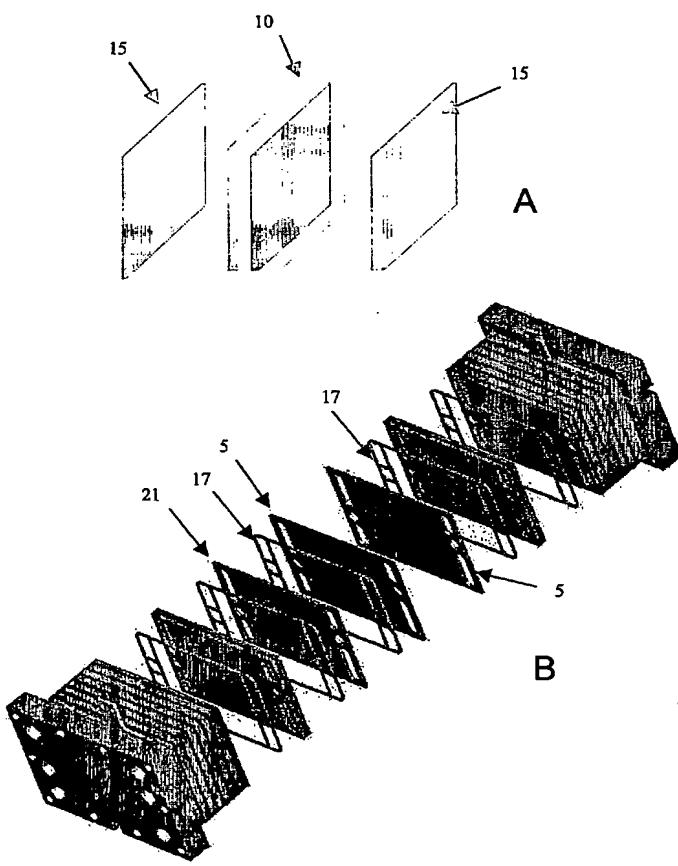
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(54) Title: PROCESS FOR SEALING PLATES IN AN ELECTROCHEMICAL CELL



(57) Abstract: There is provided a process for sealing a coolant plate to an adjacent bi-polar plate or coolant plate in an electrochemical cell. The first coolant plate comprises at least one mating region for mating with a complementary region on the adjacent plate, the adjacent plate is a second coolant plate or a bipolar plate of the electrochemical cell, and the first coolant plate and the adjacent plate each comprise a polymer and conductive filler. The process comprises the step of welding the mating region to the complementary region to create a seal formed by the polymer at the mating region and the complementary region. Welding may be done using resistance welding or vibration welding processes.

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